

积层贴片陶瓷片式电容器

C1608X5R1H474K080AB

RoHS Reach Halogen Free Pb Free

交货型号	C1608X5R1H474KT****
用途	一般等级 车载用途时为 CGA3E3X5R1H474K080AB 。
特点	General 一般 (~75V)
系列	C1608 [EIA 0603]
状态	量产体制



尺寸

长度(L)	1.60mm ±0.10mm
宽度(W)	0.80mm ±0.10mm
厚度(T)	0.80mm ±0.10mm
端子宽度(B)	0.20mm Min.
端子间隔(G)	0.30mm Min.
推荐焊盘布局(PA)	0.70mm to 1.00mm(Flow Soldering) 0.60mm to 0.80mm(Reflow Soldering)
推荐焊盘布局(PB)	0.80mm to 1.00mm(Flow Soldering) 0.60mm to 0.80mm(Reflow Soldering)
推荐焊盘布局(PC)	0.60mm to 0.80mm(Flow Soldering) 0.60mm to 0.80mm(Reflow Soldering)

电气特性

电容	470nF ±10%
额定电压	50VDC
温度特性	X5R(±15%)
耗散因数 (Max.)	5%
绝缘电阻 (Min.)	1063MΩ

其他

焊接方法	流体 回流
AEC-Q200	NO
包装形式	纸编带 (180mm卷筒)
包装个数	4000pcs

! Images are for reference only and show exemplary products.

! This PDF document was created based on the data listed on the TDK Corporation website.

! All specifications are subject to change without notice.

积层贴片陶瓷片式电容器

C1608X5R1H474K080AB

RoHS Reach Halogen Free Pb Free

特性图表 (这是参考数据，并不保证产品的特性。)

Associated Images

